1 Product profile

1.1 General description

General-purpose PIN diode in an SOD523 ultra-small SMD plastic package.

1.2 Features and benefits

- · Low diode capacitance
- · Low diode forward resistance
- AEC-Q101 qualified

1.3 Applications

· General RF applications

2 Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode		14
2	anode	1 2	- ₩- sym006
		Top view	

3 Ordering information

Table 2. Ordering information

Type number	Package			
	Name	Description	Version	
BAP51-02	-	plastic surface-mounted package; 2 leads	SOD523	

4 Marking

Table 3. Marking code

Table 5. Marking code				
Type number	Marking code			
BAP51-02	K1 ^[1]			



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[1] The marking bar indicates the cathode (see simplified outline graphic in <u>Table 1</u>).

5 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	continuous reverse voltage		-	60	V
l _F	continuous forward current		-	50	mA
P _{tot}	total power dissipation	T _{sp} ≤ 90 °C	-	715	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-65	+150	°C

6 Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
R _{th(j-sp)}	thermal resistance from junction to solder point		85	K/W

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7 Characteristics

Table 6. Characteristics

 T_i = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	ı	Min	Тур	Max	Unit
V _F	forward voltage	I _F = 50 mA	-	-	0.95	1.1	V
V _R	reverse voltage	I _R = 10 μA	5	50	-	-	V
I _R	reverse current	V _R = 50 V	-	-	-	100	nA
C _d	diode capacitance	f = 1 MHz (see Figure 1)			·	·	
		V _R = 0 V	-	-	0.4	-	pF
		V _R = 1 V	-	-	0.3	0.55	pF
		V _R = 5 V	-	-	0.2	0.35	pF
r _D	diode forward resistance	f = 100 MHz (see Figure 2)			'		
		I _F = 0.5 mA	[1]	_	5.5	9	Ω
		I _F = 1 mA	[1] _	•	3.6	6.5	Ω
		I _F = 10 mA	[1]	-	1.5	2.5	Ω

^[1] Guaranteed on AQL basis: inspection level S4, AQL 1.0.

Silicon PIN diode

8 Graphical data

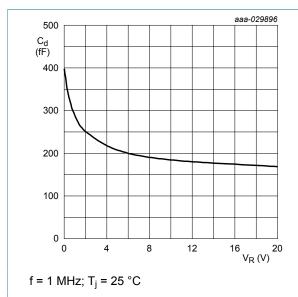
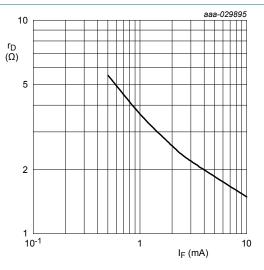
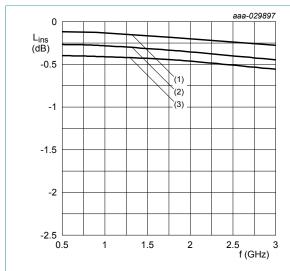


Figure 1. Diode capacitance as a function of reverse voltage (typical values)



f = 100 MHz; $T_i = 25 ^{\circ}\text{C}$.

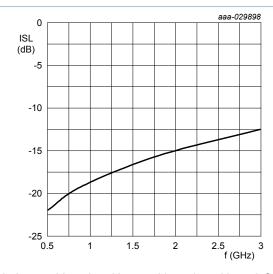
Figure 2. Diode forward resistance as a function of forward current (typical values)



Diode inserted in series with a 50 Ω stripline circuit and biased via the analyzer T-network; T_{amb} = 25 $^{\circ}C$

- (1) $I_F = 10 \text{ mA}$
- (2) $I_F = 1 \text{ mA}$
- (3) $I_F = 0.5 \text{ mA}$

Figure 3. Insertion loss of the diode in on-state as a function of frequency (typical values)



Diode zero-biased and inserted in series with a 50 Ω strip line circuit; T_{amb} = 25 $^{\circ}C$

Figure 4. Isolation of the diode in off-state as a function of frequency (typical values)

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9 Package outline

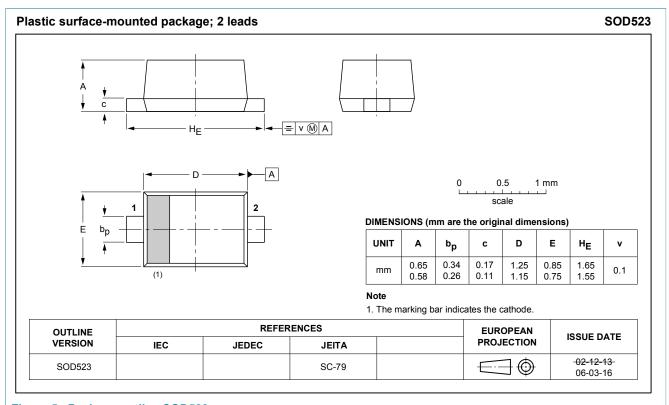


Figure 5. Package outline SOD523

10 Abbreviations

Table 7. Abbreviations

Acronym	Description
AQL	acceptable quality level
PIN	P-type, intrinsic, N-type
RF	radio frequency
S4	special inspection level 4
SMD	surface-mounted device

Silicon PIN diode

11 Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP51-02 v.4.1	20190208	Product data sheet	-	BAP51-02 v.4
Modifications:	 aligned the title o 	f the data sheet with the descri	ption on the Internet	
BAP51-02 v.4	20181126	Product data sheet	-	BAP51-02 v.3
Modifications:	 <u>Section 1.2</u> "Features and benefits has been updated. The "Legal information" pages have been updated. In table Limiting values description with V_Ris changed from forward into reverse 			
BAP51-02 v.3	20080102	Product data sheet	-	-

Silicon PIN diode

12 Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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Silicon PIN diode

Contents

1	Product profile	1
1.1	General description	
1.2	Features and benefits	1
1.3	Applications	1
2	Pinning information	1
3	Ordering information	
4	Marking	
5	Limiting values	
6	Thermal characteristics	
7	Characteristics	3
8	Graphical data	4
9	Package outline	
10	Abbreviations	
11	Revision history	
12	Legal information	

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